

Title (en)

SINTERED BODY OF TiAl INTERMETALLIC COMPOUND AND METHOD FOR PRODUCING SINTERED BODY OF TiAl INTERMETALLIC COMPOUND

Title (de)

SINTERKÖRPER AUS EINER INTERMETALLISCHEN TIAL-VERBINDUNG UND VERFAHREN ZUR HERSTELLUNG EINES SINTERKÖRPERS AUS EINER INTERMETALLISCHEN TIAL-VERBINDUNG

Title (fr)

CORPS FRITTÉ DE COMPOSÉ INTERMÉTALLIQUE TiAl, ET PROCÉDÉ DE PRODUCTION DE CORPS FRITTÉ DE COMPOSÉ INTERMÉTALLIQUE TiAl

Publication

**EP 3415648 A1 20181219 (EN)**

Application

**EP 17778878 A 20170221**

Priority

- JP 2016075932 A 20160405
- JP 2017006390 W 20170221

Abstract (en)

The sintered density of a TiAl-based intermetallic sintered compact is improved. A method for producing a TiAl-based intermetallic sintered compact includes sintering TiAl-based powder to produce the TiAl-based intermetallic sintered compact, the TiAl-based powder containing a TiAl-based intermetallic compound in which Ti and Al are bonded and an additional metal. The additional metal is Ni, or Ni and Fe.

IPC 8 full level

**C22C 1/04** (2006.01); **B22F 1/10** (2022.01); **B22F 3/02** (2006.01); **B22F 3/10** (2006.01); **C22C 1/00** (2006.01); **C22C 14/00** (2006.01); **C22C 21/00** (2006.01)

CPC (source: EP US)

**B22F 1/10** (2022.01 - EP US); **B22F 3/16** (2013.01 - US); **B22F 3/225** (2013.01 - EP US); **C22C 1/00** (2013.01 - EP US); **C22C 1/0416** (2013.01 - EP US); **C22C 1/0458** (2013.01 - EP US); **C22C 1/047** (2023.01 - EP US); **C22C 14/00** (2013.01 - EP US); **C22C 21/00** (2013.01 - EP US); **B22F 2301/052** (2013.01 - US); **B22F 2301/205** (2013.01 - US); **B22F 2301/40** (2013.01 - US); **B22F 2304/10** (2013.01 - US); **B22F 2998/10** (2013.01 - US)

Designated contracting state (EPC)

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Designated extension state (EPC)

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